

The N3XT Technology for Brain-Inspired Computing



H.-S. Philip Wong
Stanford University



Source: Google



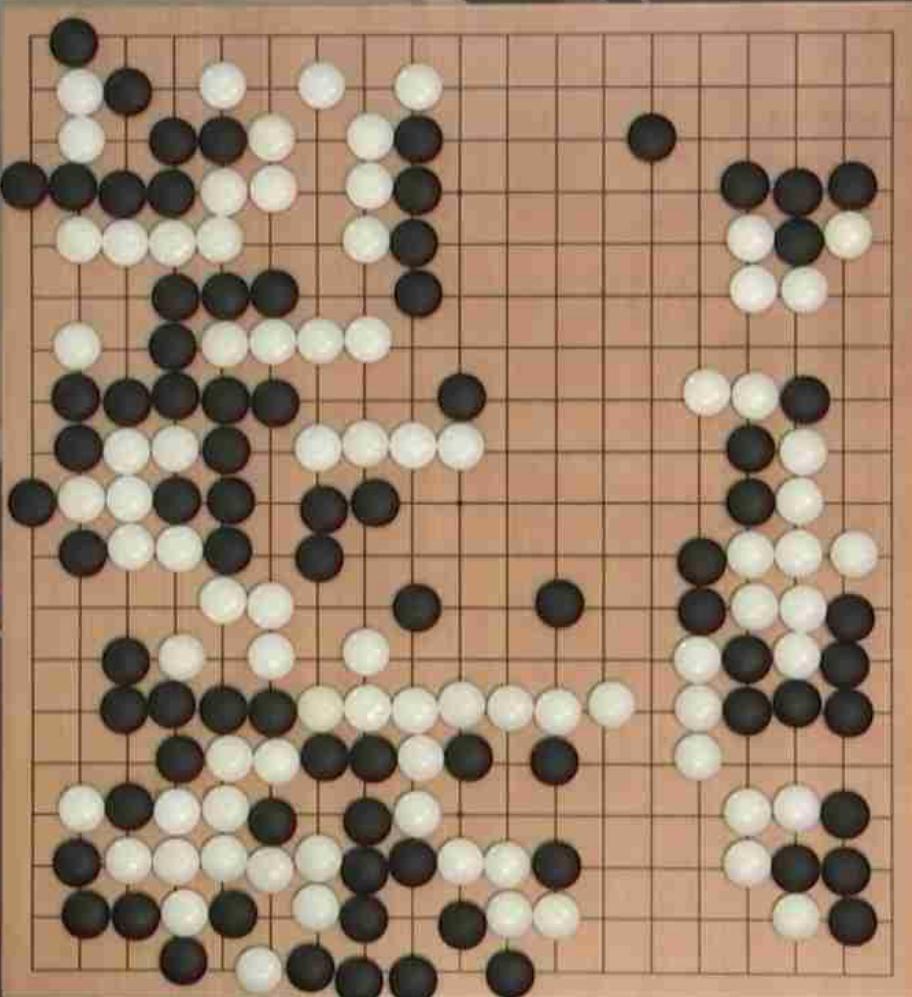


Source: BDC Magazine



1988 Winter Olympic Games in Calgary, Canada





ALPHAGO
00:10:29



LEE SEDOL
00:01:00

100's of kW



Source: Google

Scale Up Requires Energy Efficiency

	Application	Hardware used	Estimated power consumption
Large scale	Emulating 4.5% of human brain: 10^{13} synapses, 10^9 neurons	Blue Gene/P: 36,864 nodes, 147,456 cores	2.9 MW (LINPACK)
	Deep sparse autoencoder: 10^9 synapses, 10M images	1,000 CPUs (16,000 cores)	~100 kW (cores only)
Small to moderate scale	Convolutional neural net with 60M synapses, 650K neurons	2 GPUs	1,200 W
	Restricted Boltzmann Machine: 28M synapses; 69,888 neurons	GPU	550 W
		CPU	65 W
	Processing 1 s of speech using deep neural network	GPU	238 W
		CPU (4 cores)	80 W





A Nanotechnology-Inspired Grand Challenge for Future Computing

OCTOBER 20, 2015 AT 6:00 AM ET BY LLOYD WHITMAN, RANDY BRYANT, AND TOM KALIL



Summary: Today, the White House is announcing a grand challenge to develop transformational computing capabilities by combining innovations in multiple scientific disciplines.

In June,
suggest
over 10
three A
[Compu](#)

These nanotechnology innovations will have to be developed in close coordination with new computer architectures, and will likely be informed by our growing understanding of the brain—a remarkable, fault-tolerant system that consumes less power than an incandescent light bulb.

Approaches of Neuromorphic Hardware



Approaches of Neuromorphic Hardware

Biology-based
models /
algorithms

Conventional
ML algorithms



Approaches of Neuromorphic Hardware

**Neuromorphic
hardware**

**Conventional
hardware (CPU, GPU,
supercomputers, etc)**



Approaches of Neuromorphic Hardware

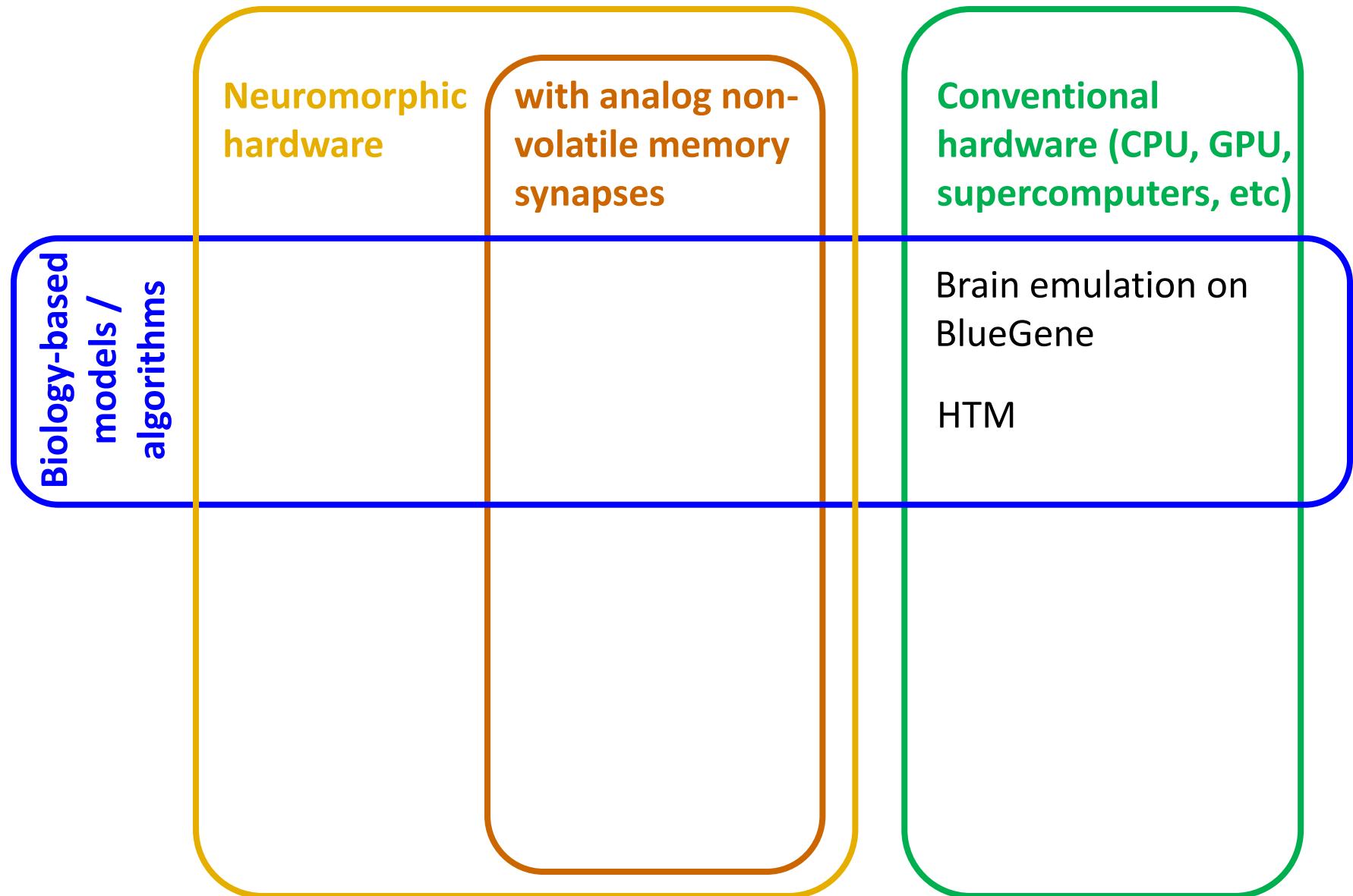
Neuromorphic hardware

with analog non-volatile memory synapses

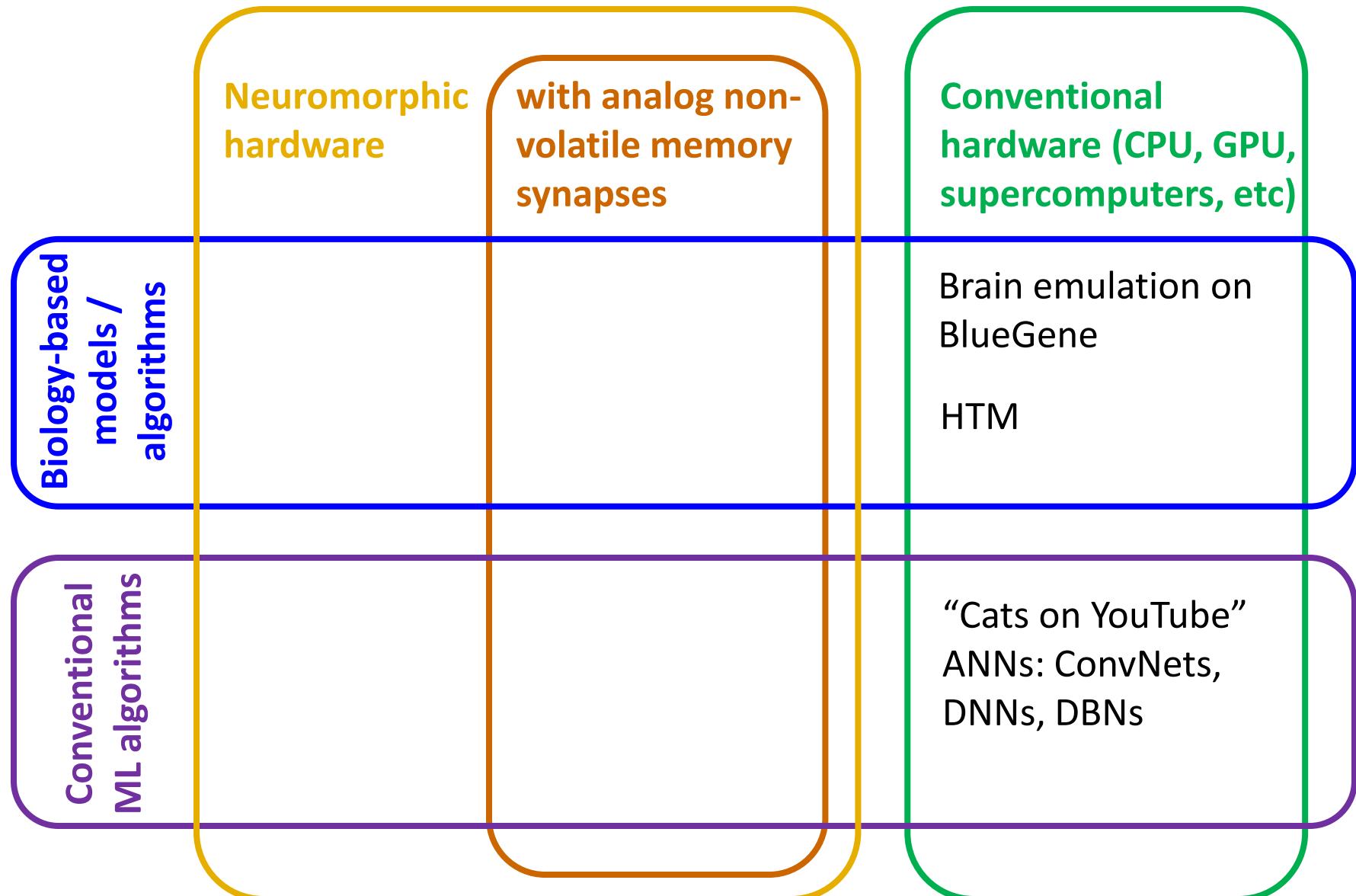
Conventional hardware (CPU, GPU, supercomputers, etc)



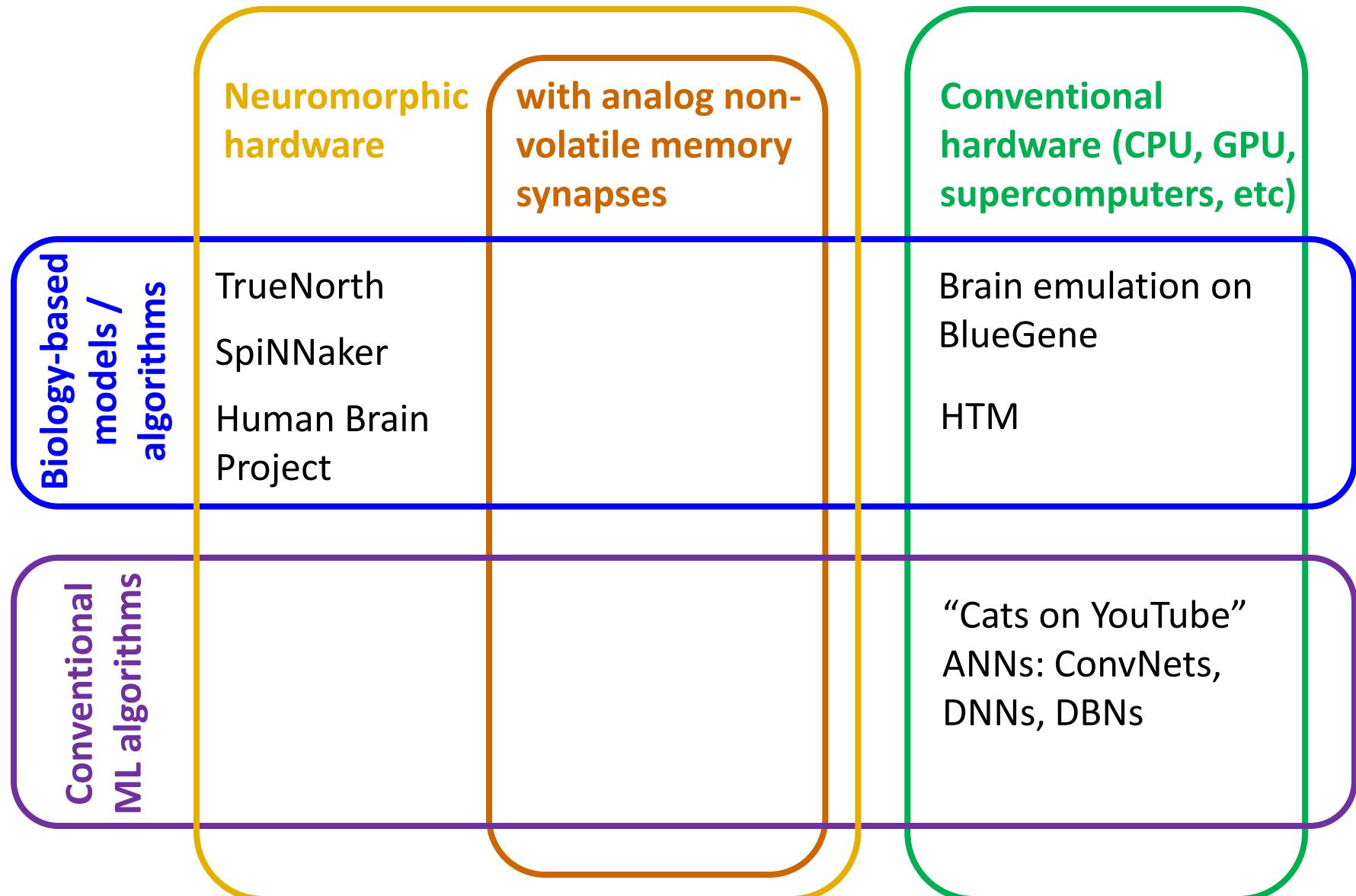
Approaches of Neuromorphic Hardware



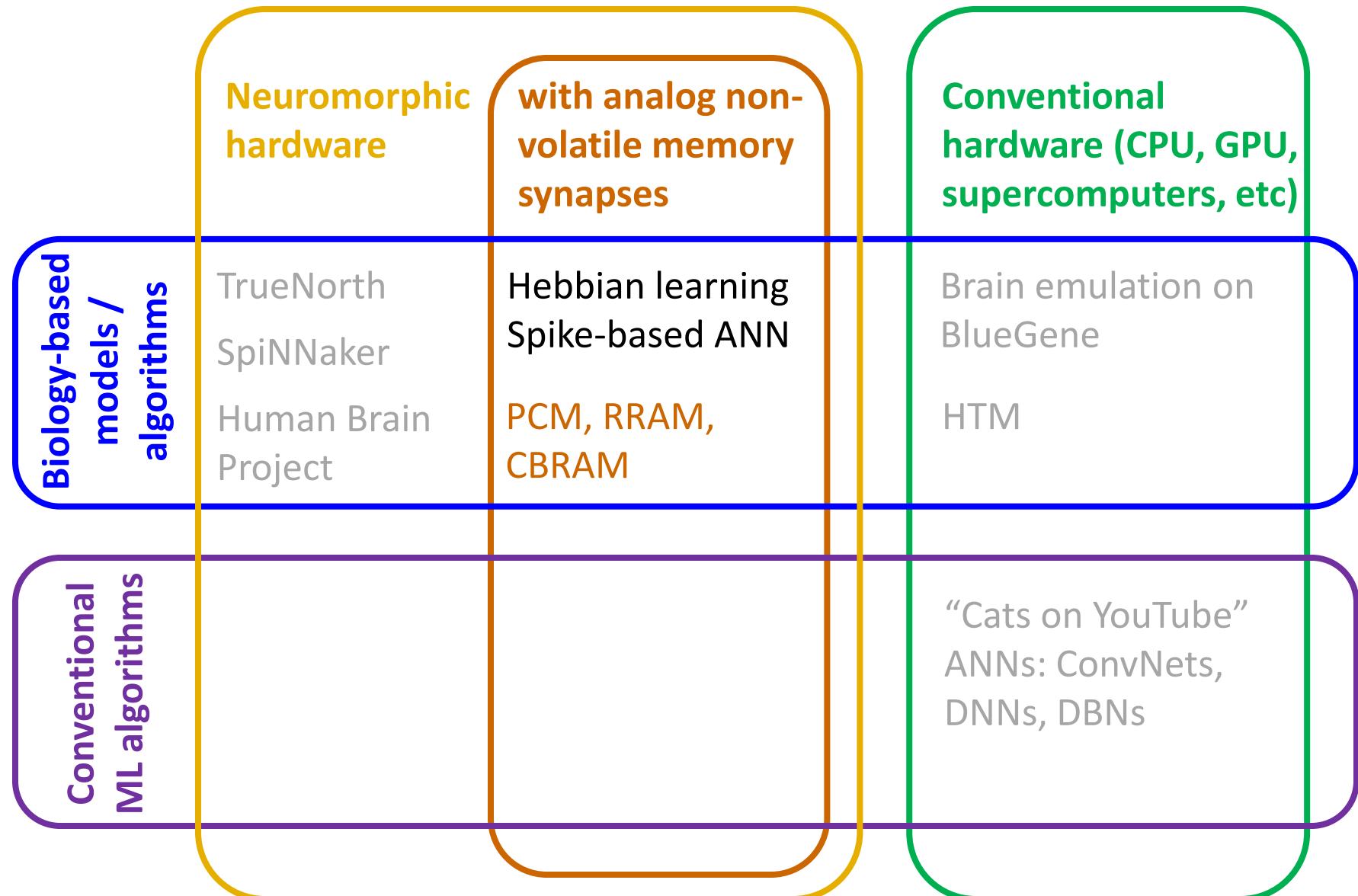
Approaches of Neuromorphic Hardware



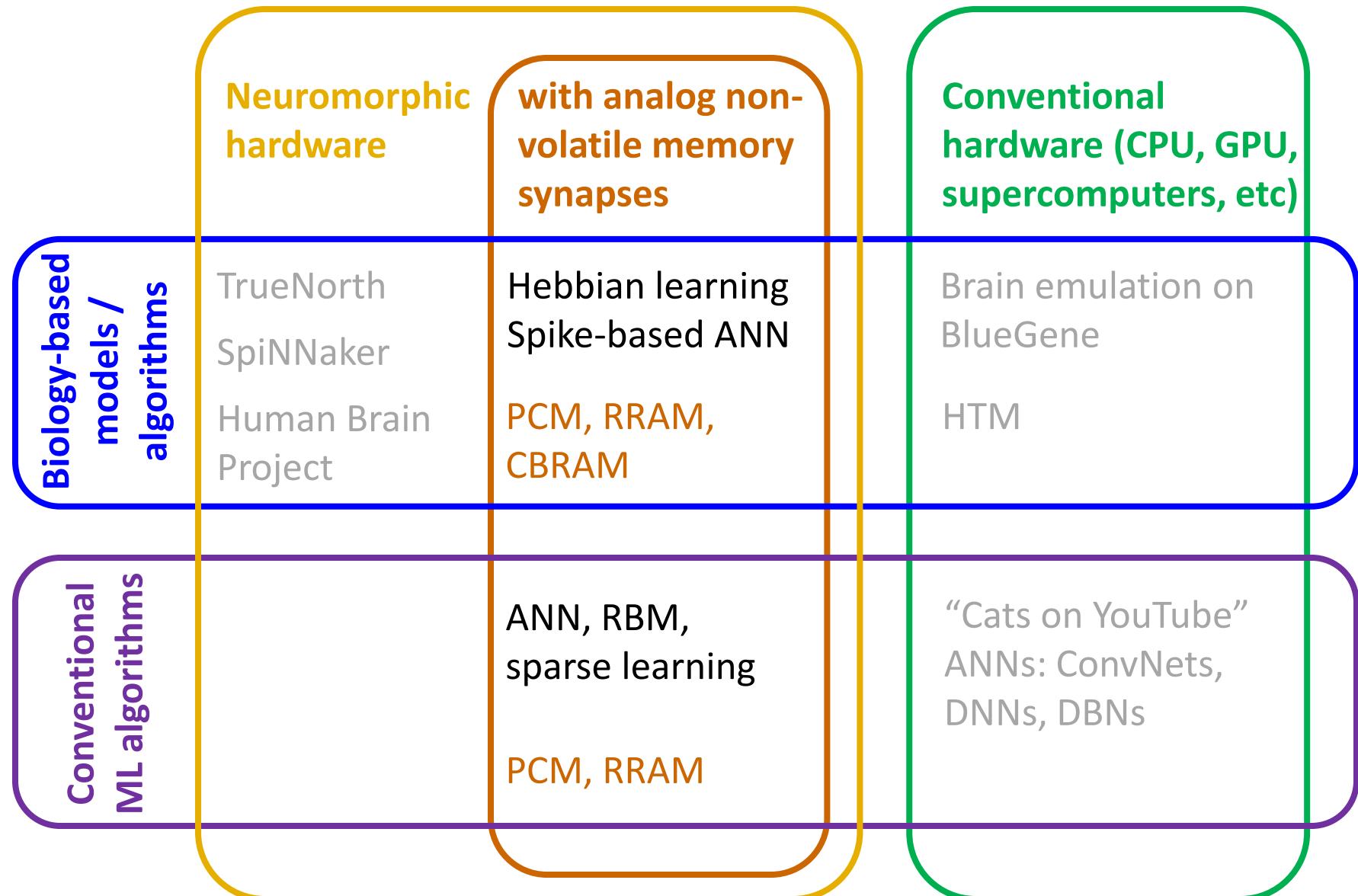
Approaches of Neuromorphic Hardware



Approaches of Neuromorphic Hardware



Approaches of Neuromorphic Hardware





A Nanotechnology-Inspired Grand Challenge for Future Computing

OCTOBER 20, 2015 AT 6:00 AM ET BY LLOYD WHITMAN, RANDY BRYANT, AND TOM KALIL



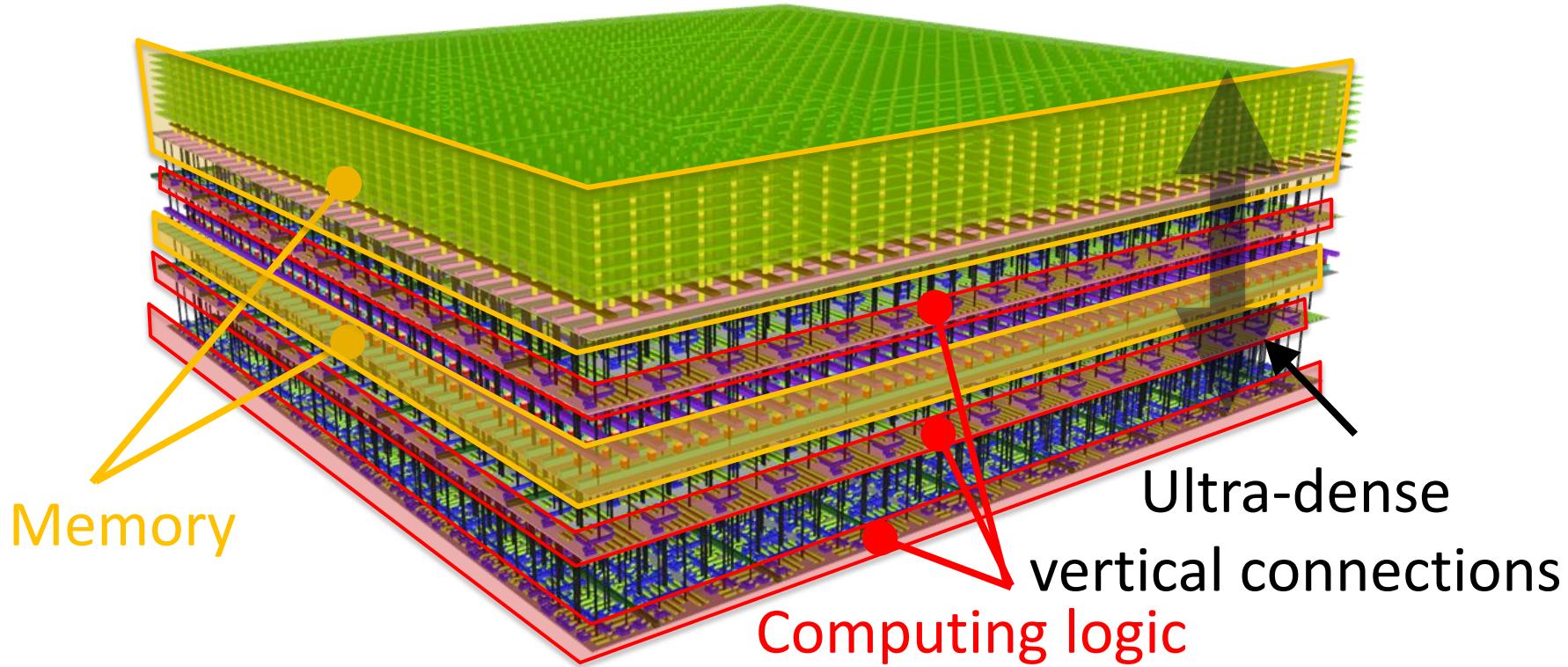
Summary: Today, the White House is announcing a grand challenge to develop transformational computing capabilities by combining innovations in multiple scientific disciplines.

In June, the Office of Science and Technology Policy issued a [Request for Information](#) seeking suggestions for *Nanotechnology-Inspired Grand Challenges for the Next Decade*. After considering over 100 responses from the public and three Administration agencies, the White House has selected a set of breakthroughs to pursue.

Many of these breakthroughs will require new kinds of nanoscale devices and materials integrated into **three-dimensional systems** and may take a decade or more to achieve.

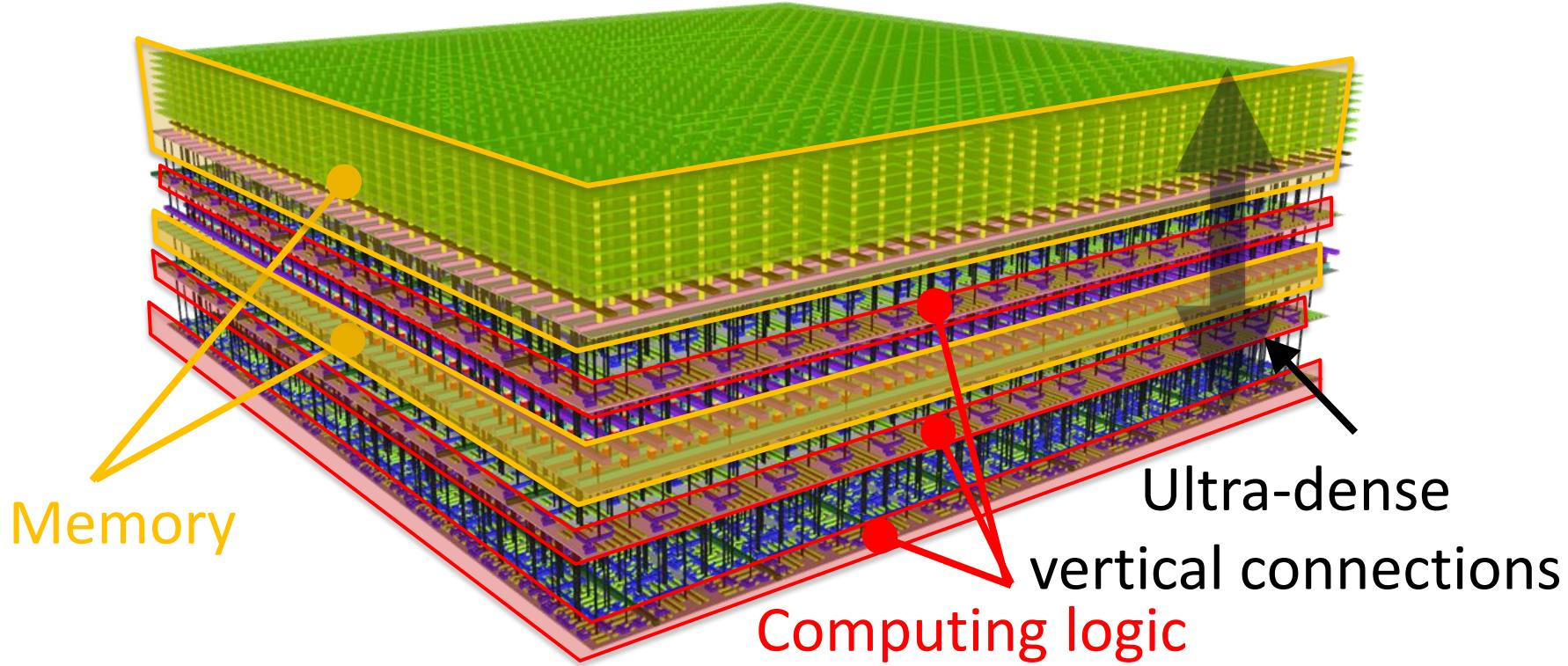
N3XT Nanosystems

Computation immersed in memory



N3XT Nanosystems

Computation immersed in memory



Impossible with today's technologies

N3XT: Computation Immersed in Memory

3D Resistive RAM

Massive storage

1D CNFET, 2D FET

Compute, RAM access

MRAM

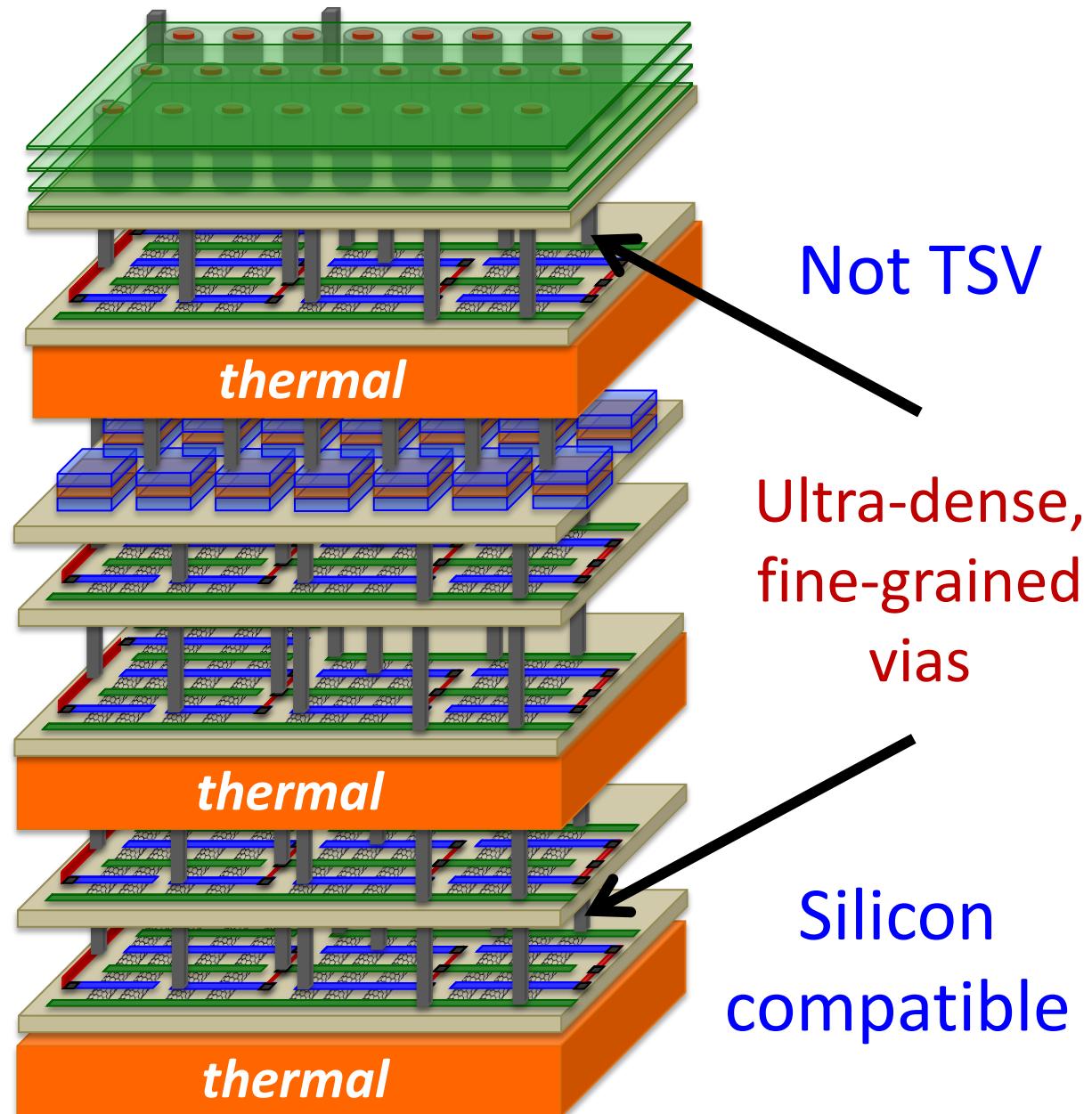
Quick access

1D CNFET, 2D FET

Compute, RAM access

1D CNFET, 2D FET

Compute, Power,
Clock





Energy-Efficient Abundant-Data Computing: The N3XT 1,000×

Aly et al., *IEEE Computer*, 2015

Mohamed M. Sabry Aly, Mingyu Gao, Gage Hills, Chi-Shuen Lee, Greg Pitner, Tony F. Wu, and Mehdi Asheghi, Stanford University

Jeff Bokor, University of California, Berkeley

Franz Franchetti, Carnegie Mellon University

Kenneth E. Goodson and Christos Kozyrakis, Stanford University

Igor Markov, University of Michigan, Ann Arbor

Kunle Olukotun, Stanford University

Larry Pileggi, Carnegie Mellon University

Eric Pop, Stanford University

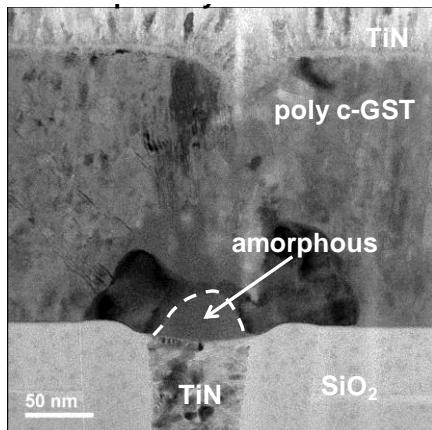
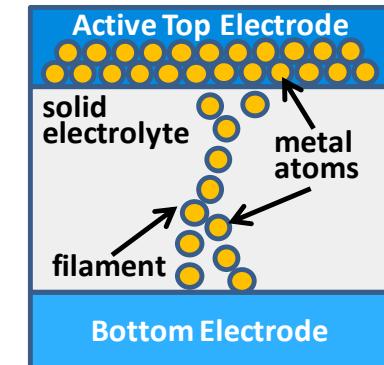
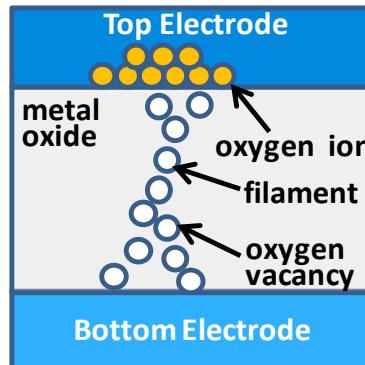
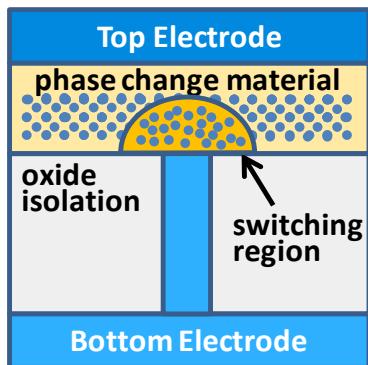
Jan Rabaey, University of California, Berkeley

Christopher Ré, H.-S. Philip Wong, and Subhasish Mitra, Stanford University

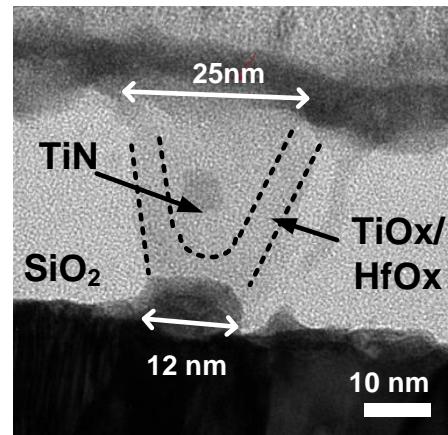
Next-generation information technologies will process unprecedented amounts of loosely structured data that overwhelm existing computing systems. N3XT improves the energy efficiency of abundant-data applications 1,000-fold by using new logic and memory technologies, 3D integration with fine-grained connectivity, and new architectures for computation immersed in memory.



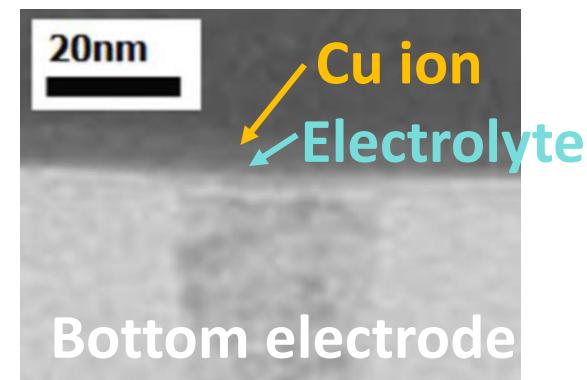
Non-Volatile Memory (NVM)



Phase change
memory (PCM)



Metal oxide resistive
switching memory (RRAM)



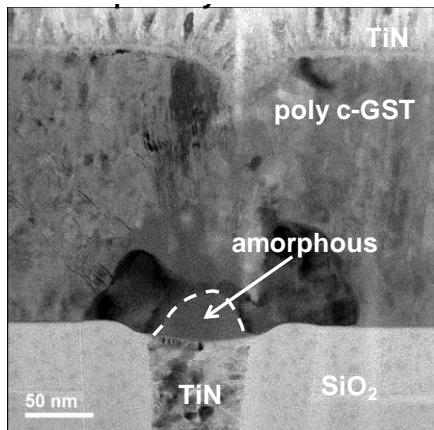
Conductive bridge
memory (CBRAM)

D. Kuzum et al., *Nano Lett.* 2013, Y. Wu et al., *IEDM* 2013; A. Calderoni et al., *IMW* 2014

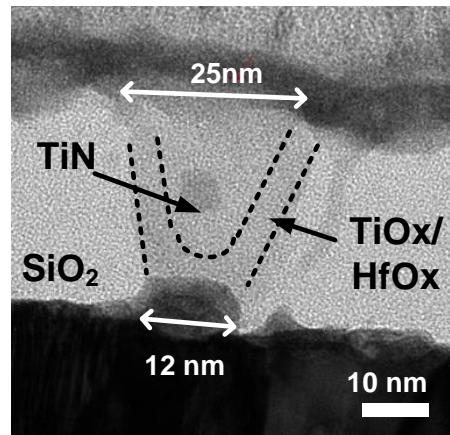


Non-Volatile Memory (NVM) → Synapse

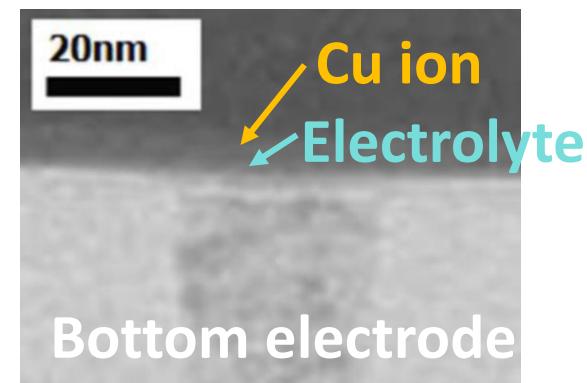
- Analog programmable
- Scalable to a few nm
- Stack in 3D



Phase change
memory (PCM)



Metal oxide resistive
switching memory (RRAM)



Conductive bridge
memory (CBRAM)

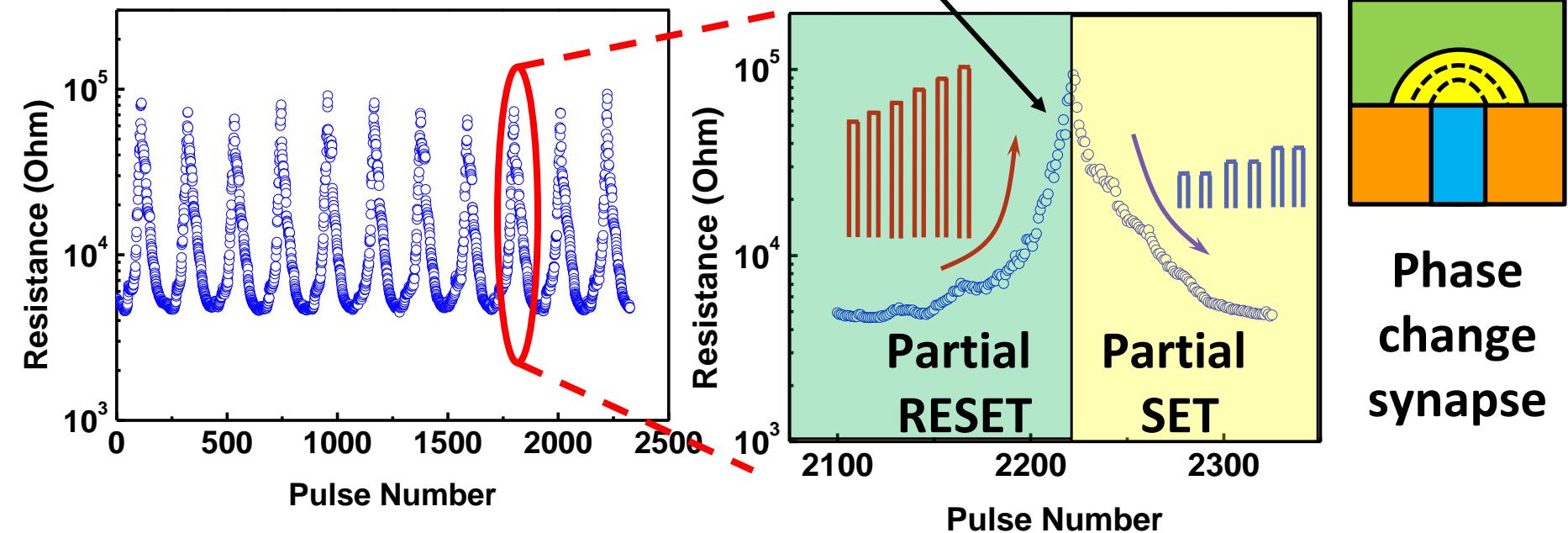
D. Kuzum et al., *Nano Lett.* 2013, Y. Wu et al., *IEDM* 2013; A. Calderoni et al., *IMW* 2014



Nanoscale Memory as Synaptic Weights

Synaptic updates in the brain: basis for learning
Requirement: analog resistance change

100-step grey scale (1% resolution)



D. Kuzum *et al.*, *Nano Lett.*, p. 2179 (2012)



Nanoscale Memory Can Emulate Biological Synaptic Behavior

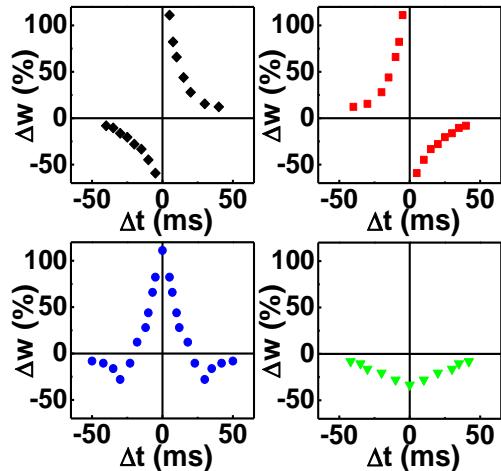
STDP (spike-timing-dependent plasticity)

D. Kuzum *et al.*, *Nano Lett.*, p. 2179 (2012)



Nanoscale Memory Can Emulate Biological Synaptic Behavior

STDP (spike-timing-dependent plasticity)



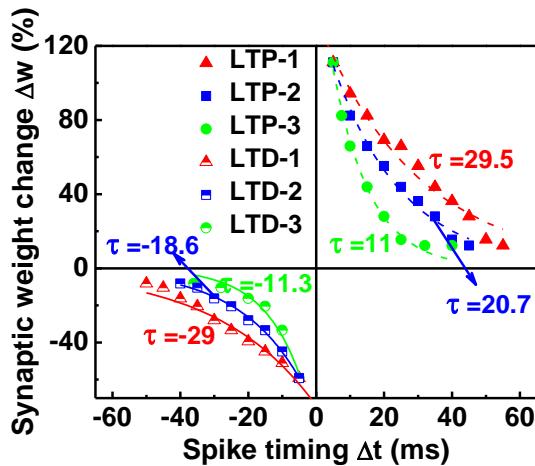
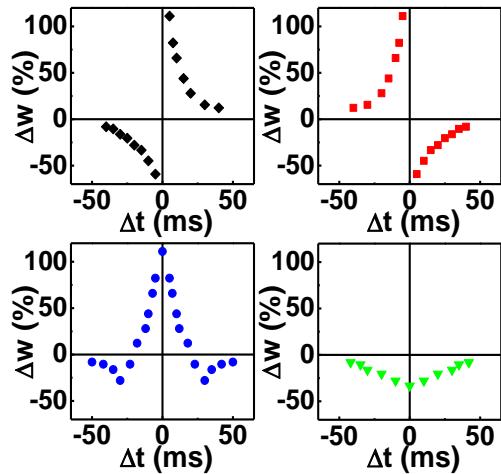
Various STDP kernels

D. Kuzum *et al.*, *Nano Lett.*, p. 2179 (2012)



Nanoscale Memory Can Emulate Biological Synaptic Behavior

STDP (spike-timing-dependent plasticity)



Various STDP kernels

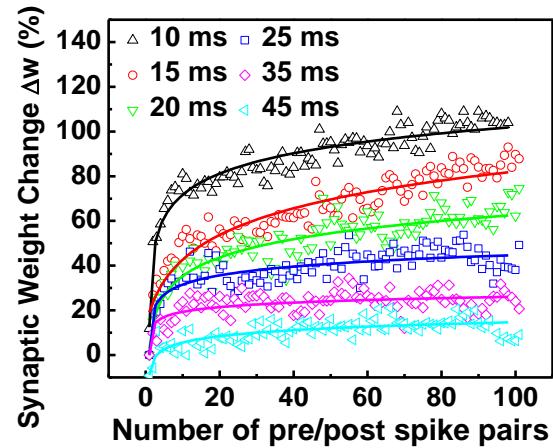
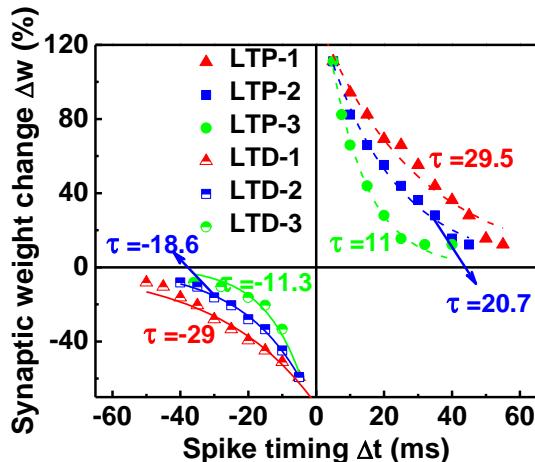
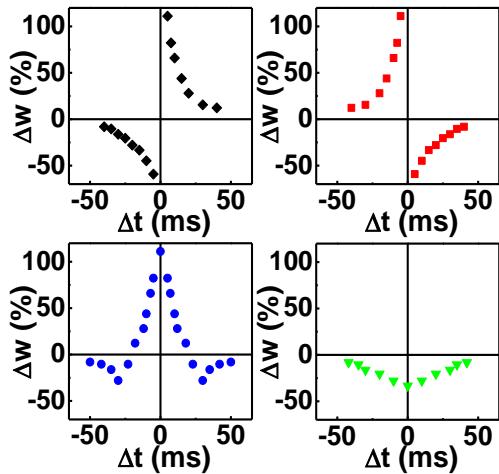
Various time constants

D. Kuzum *et al.*, *Nano Lett.*, p. 2179 (2012)



Nanoscale Memory Can Emulate Biological Synaptic Behavior

STDP (spike-timing-dependent plasticity)



Various STDP kernels

Various time constants

Weight update saturation



Hyper Dimensional (HD) Computing

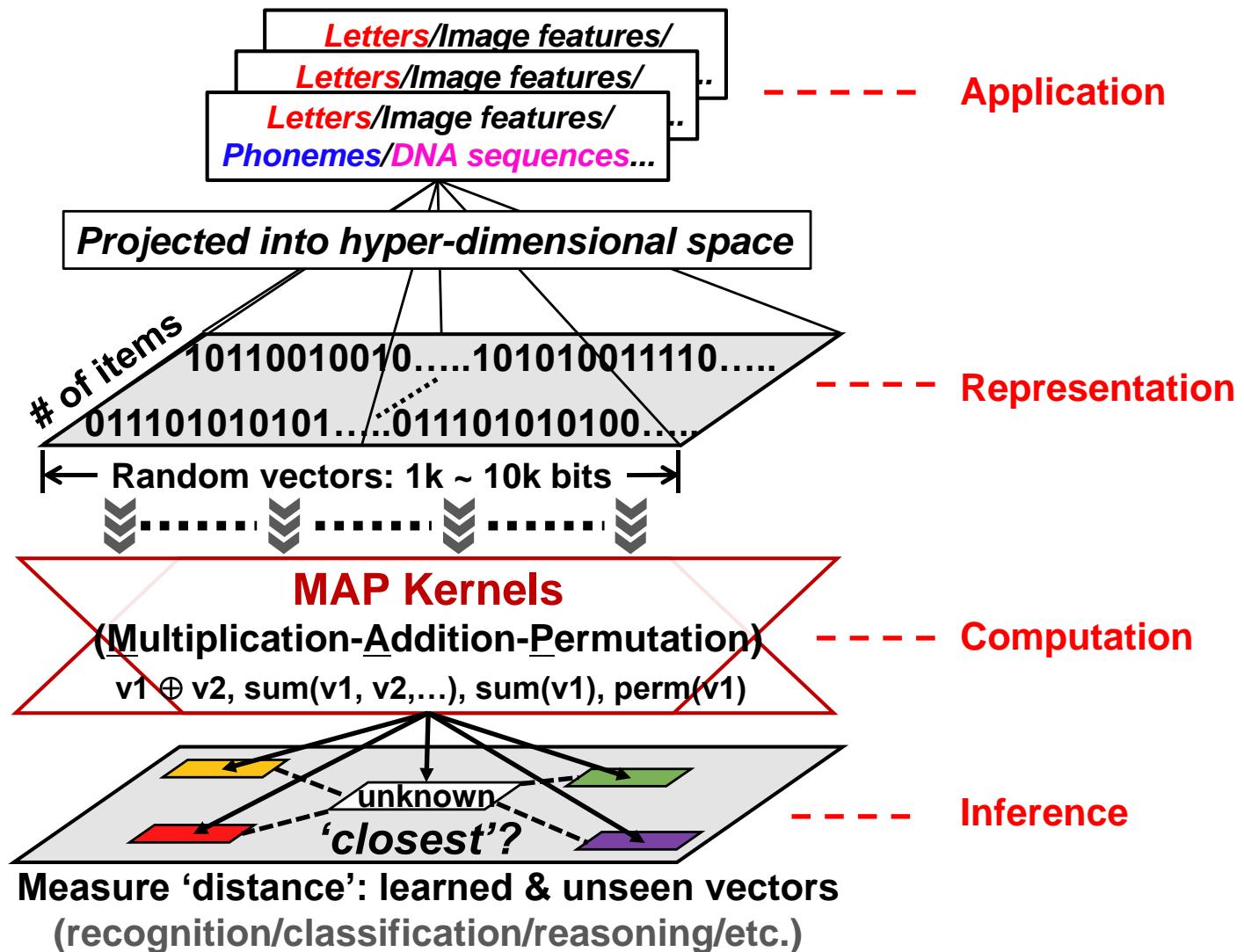
Elements of Hyper dimensional Computing:

Also known as vector symbolic architectures or holographic reduced representation (Kanerva, *Cognitive Computation*, 1(2):139-159,2009)

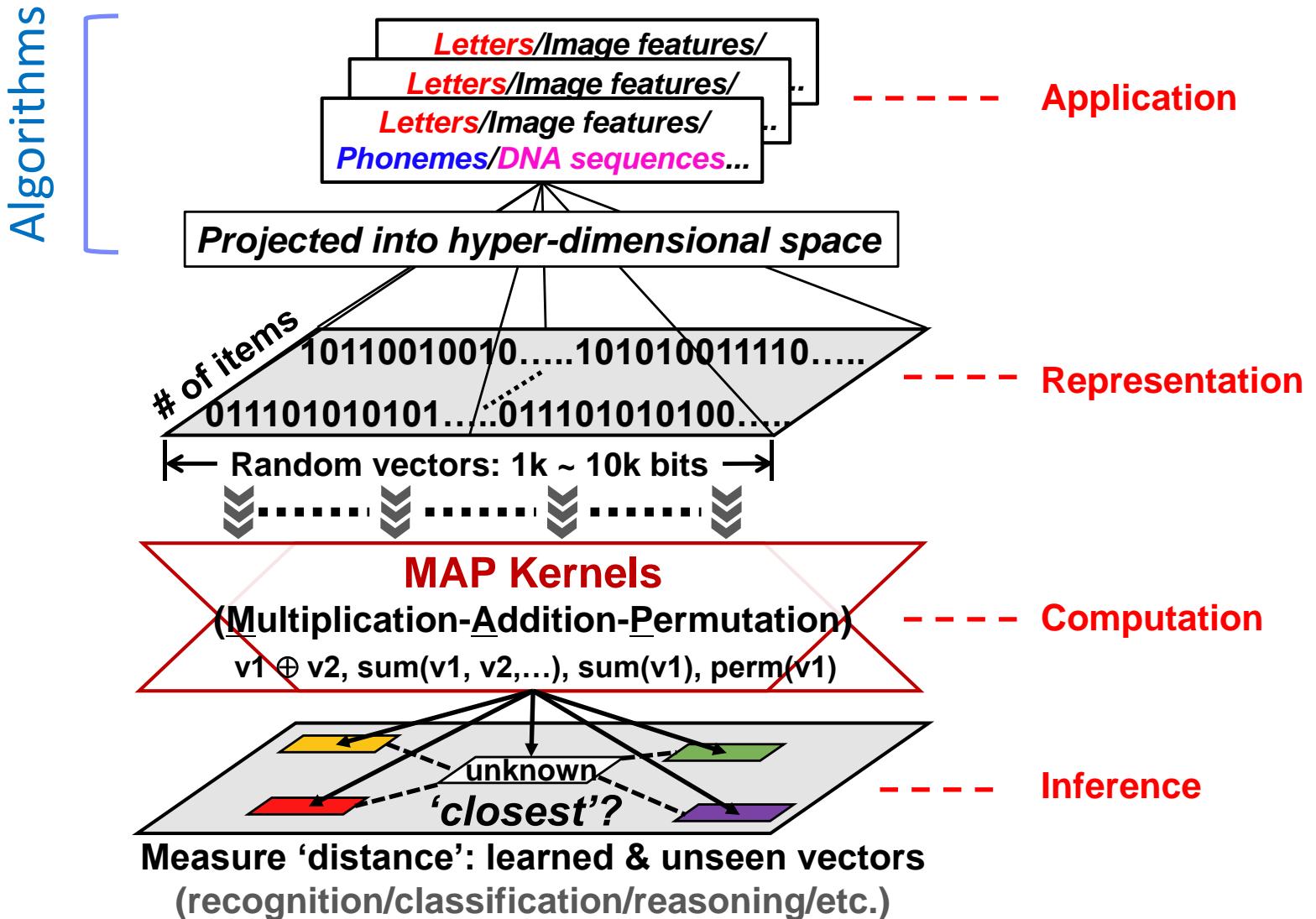
- Information is represented by High-dimensional representation (e.g., $D = 10,000$)
- Variables and values are combined into a “holistic” record using vector algebra:
 - Multiplication for Binding
 - Addition for Bundling
- Composed vector can in turn become a component in further composition
- Holistic record is decoded with (inverse) multiplication
- Approximate results of vector operations are identified with exact ones using content-addressable memory



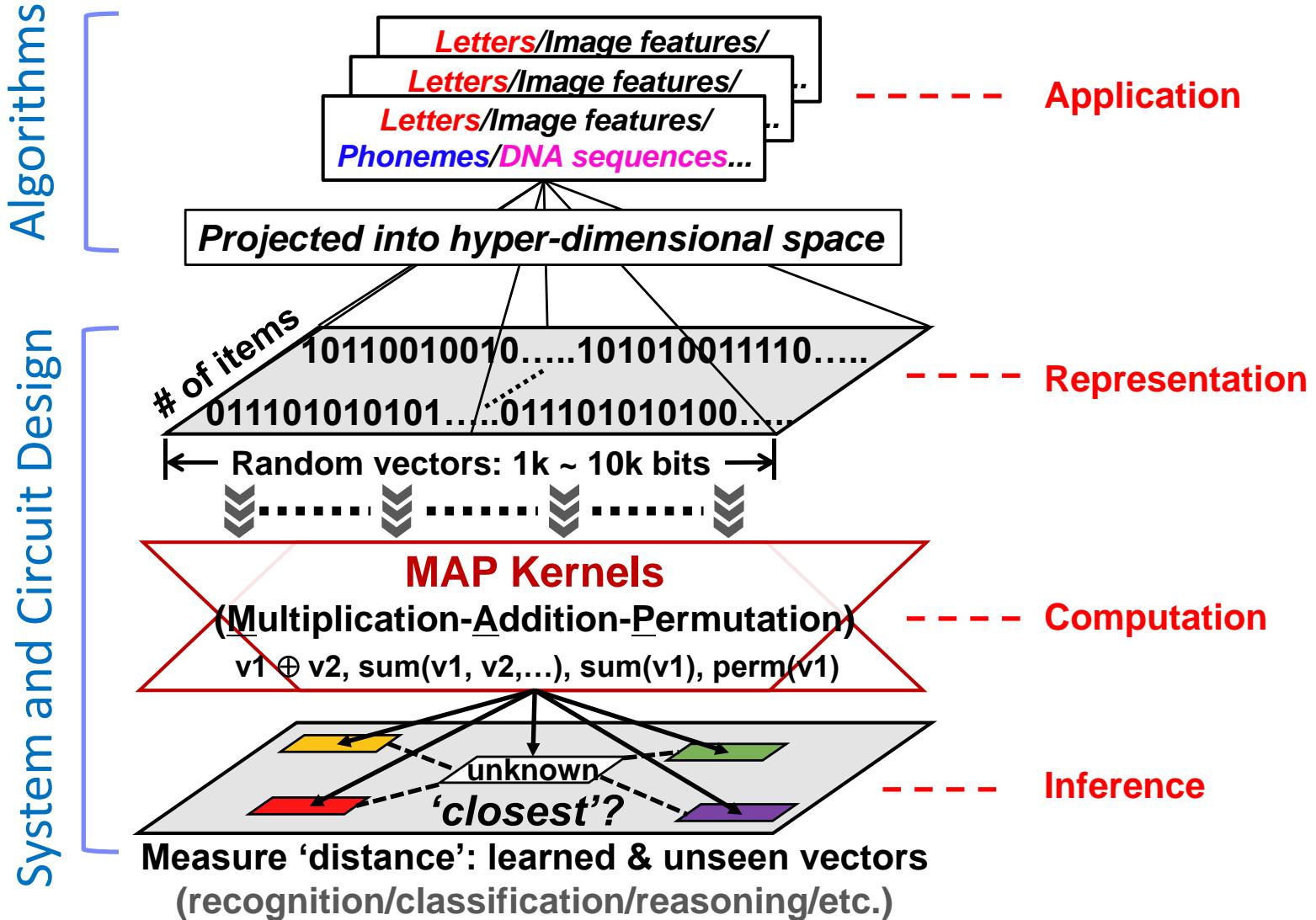
HD Computing layers



HD Computing layers



HD Computing layers



HD Computing layers

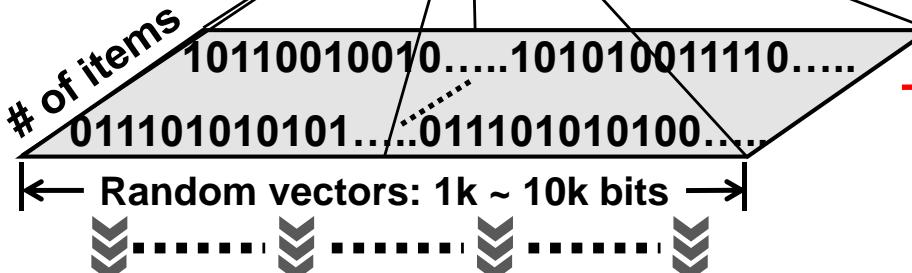
Associative memory enabled by
novel device technologies

Algorithms

*Letters/Image features/
Letters/Image features/
Letters/Image features/
Phonemes/DNA sequences...*

Application

Projected into hyper-dimensional space



Representation

MAP Kernels

(Multiplication-Addition-Permutation)

$v1 \oplus v2$, $\text{sum}(v1, v2, \dots)$, $\text{sum}(v1)$, $\text{perm}(v1)$

Computation



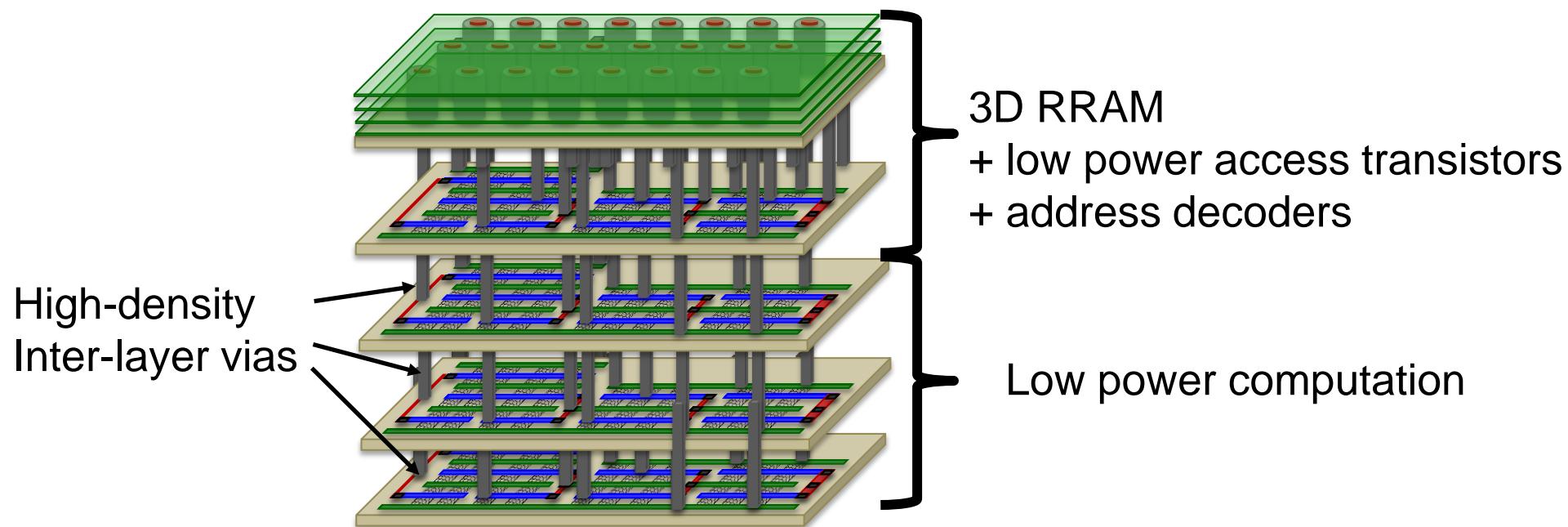
Inference

Measure 'distance': learned & unseen vectors
(recognition/classification/reasoning/etc.)



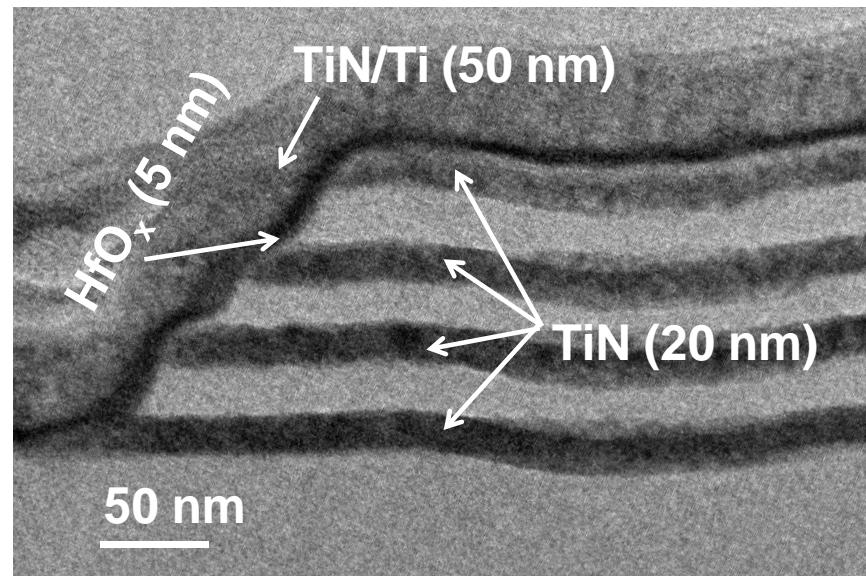
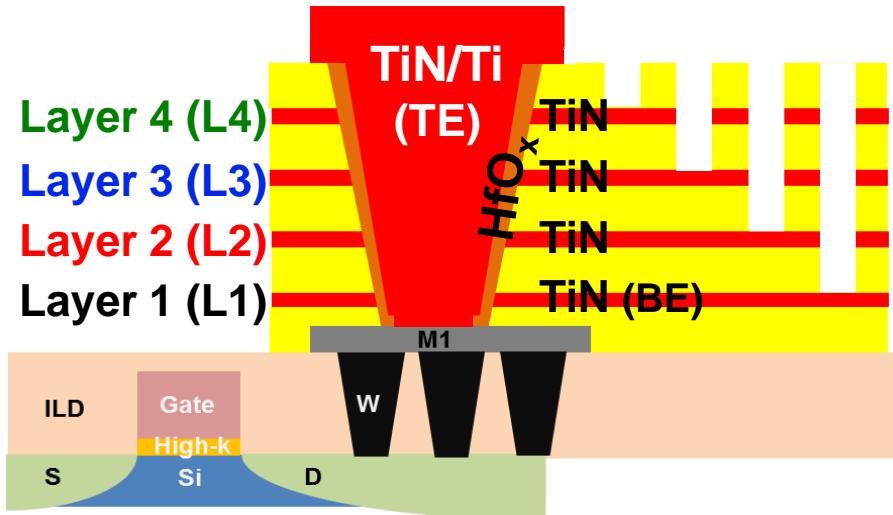
Hyperdimensional (HD) Computing

- Monolithic 3D enables
 - Energy-efficient classification
 - Area efficient HD projection
- use RRAM variability & stochastic switching



3D Enables In-Memory Computing

3D RRAM with FinFET BL select

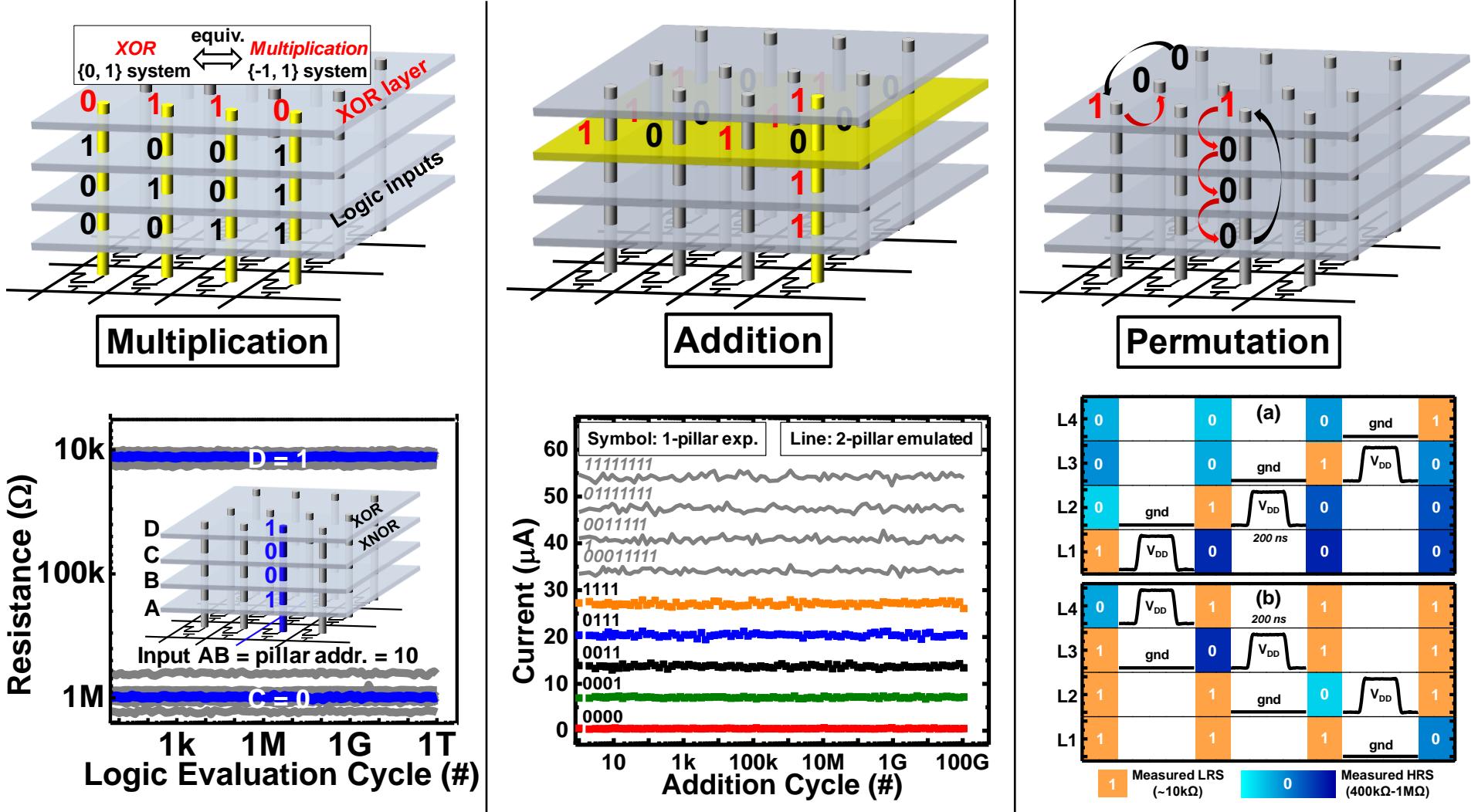


H. Li *et al.*, Symp. VLSI Tech., 2016

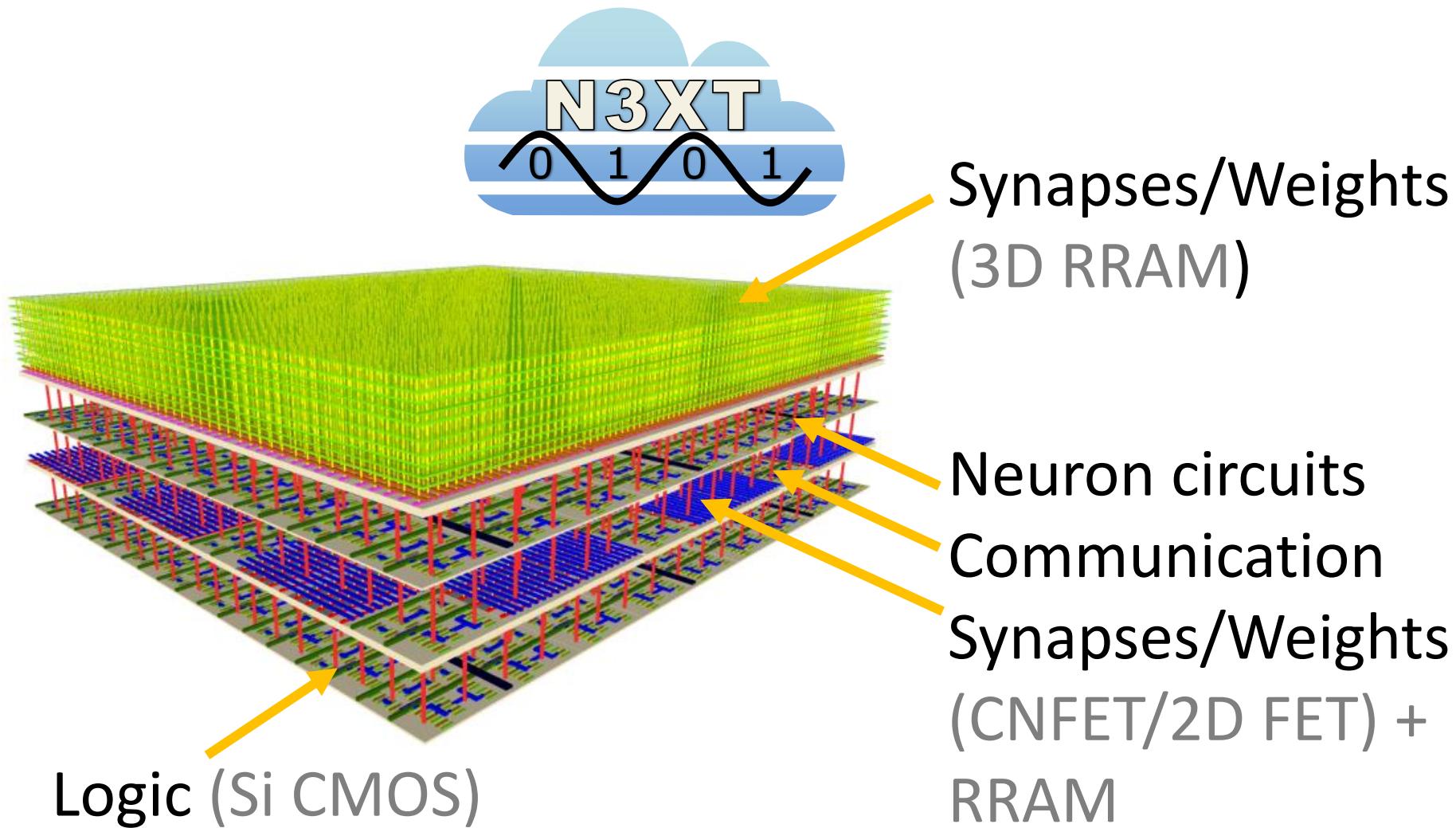


MAP Kernels: 3D RRAM Approach

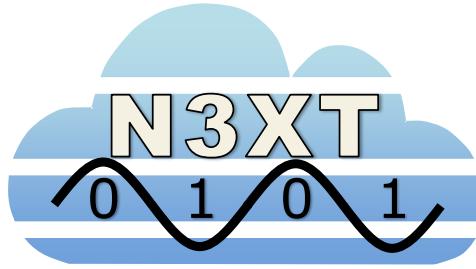
Key HD operations: multiplication, addition, permutation



3D Integration of Memory and Logic Circuits within the Same Layer & Across Layers



Nano-Engineered Computing Systems Technology



COVER FEATURE REBOOTING COMPUTING



Mehmet M. Aly et al., Weigao Fan, Kagan Halcioglu, Tony W. Wu, and Murali Anagnos, Stanford University

Jeff Karpis, University of California, Berkeley

Jeffrey P. Bigham, Carnegie Mellon University

Karen E. Crosson and Christos Kozyrakis, Stanford University

Kurt Keutzer, University of California, Berkeley

Larry Fleischman, Carnegie Mellon University

Jon Holmes, University of California, Berkeley

Christopher He, H.-S. Philip Wong, and Sudarshan Mehta, Stanford University

Next-generation information technologies will process

unprecedented amounts of loosely structured data that

overwhelm existing computing systems. N3XT improves

the energy efficiency of abundant-data applications

1,000-fold by using new logic and memory technologies,

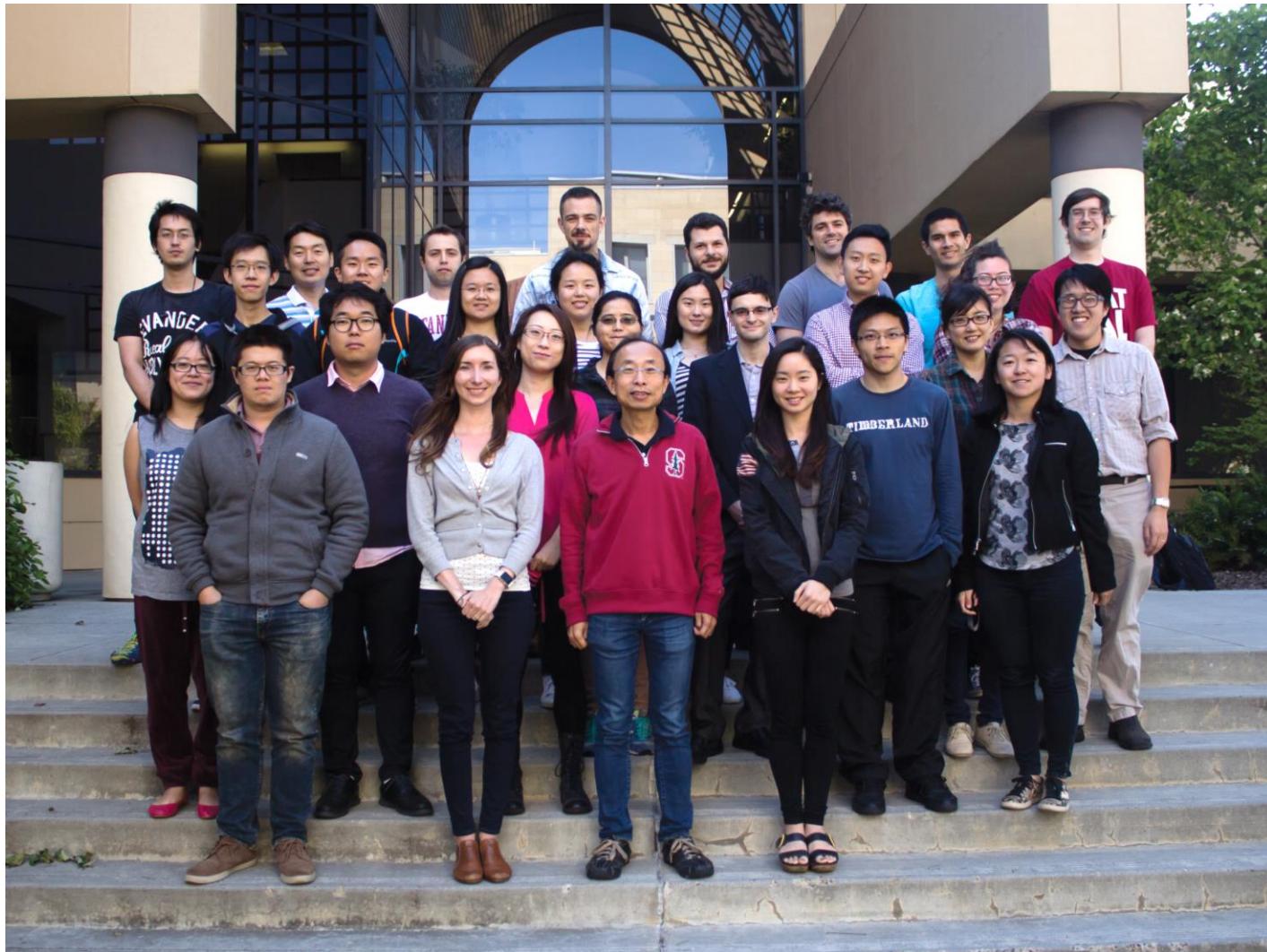
SDI integration with fine-grained connectivity, and new

architectures for computation immersed in memory.

Aly et al., *IEEE Computer*, 2015



Students and Post-Docs



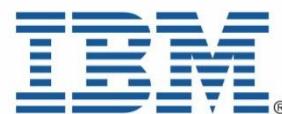
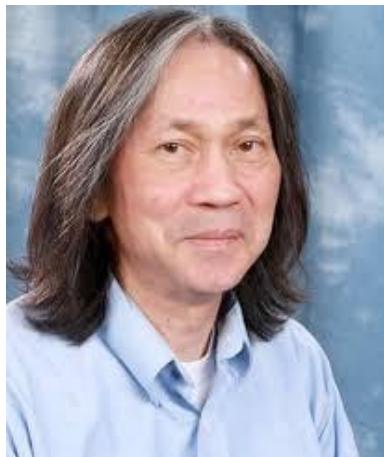
Collaborators



Gert Cauwenberghs
Siddharth Joshi
Emre Neftci
(UC San Diego)



Jinfeng Kang
(Peking U)



Chung Lam
SangBum Kim
Matt Brightsky



K.S. Lee, J.M. Shieh, W.K. Yen... (NDL, Taiwan)



A Member of **NARLabs**
National Nano Device Laboratories

Sponsors

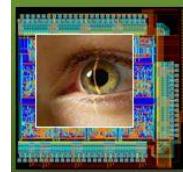


STARnet

SONIC



E2CDA “Engima”



Visual Cortex on Silicon

<http://www.cse.psu.edu/research/visualcortexonsilicon.expedition/>
Supported by National Science Foundation Expeditions in Computing Program

Stanford | SystemX Alliance

Stanford | Non-Volatile Memory Technology Research Initiative

Stanford SystemX Alliance



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Non-Volatile Memory Technology Research Initiative (NMTRI) @ Stanford University

SanDisk

MICRON

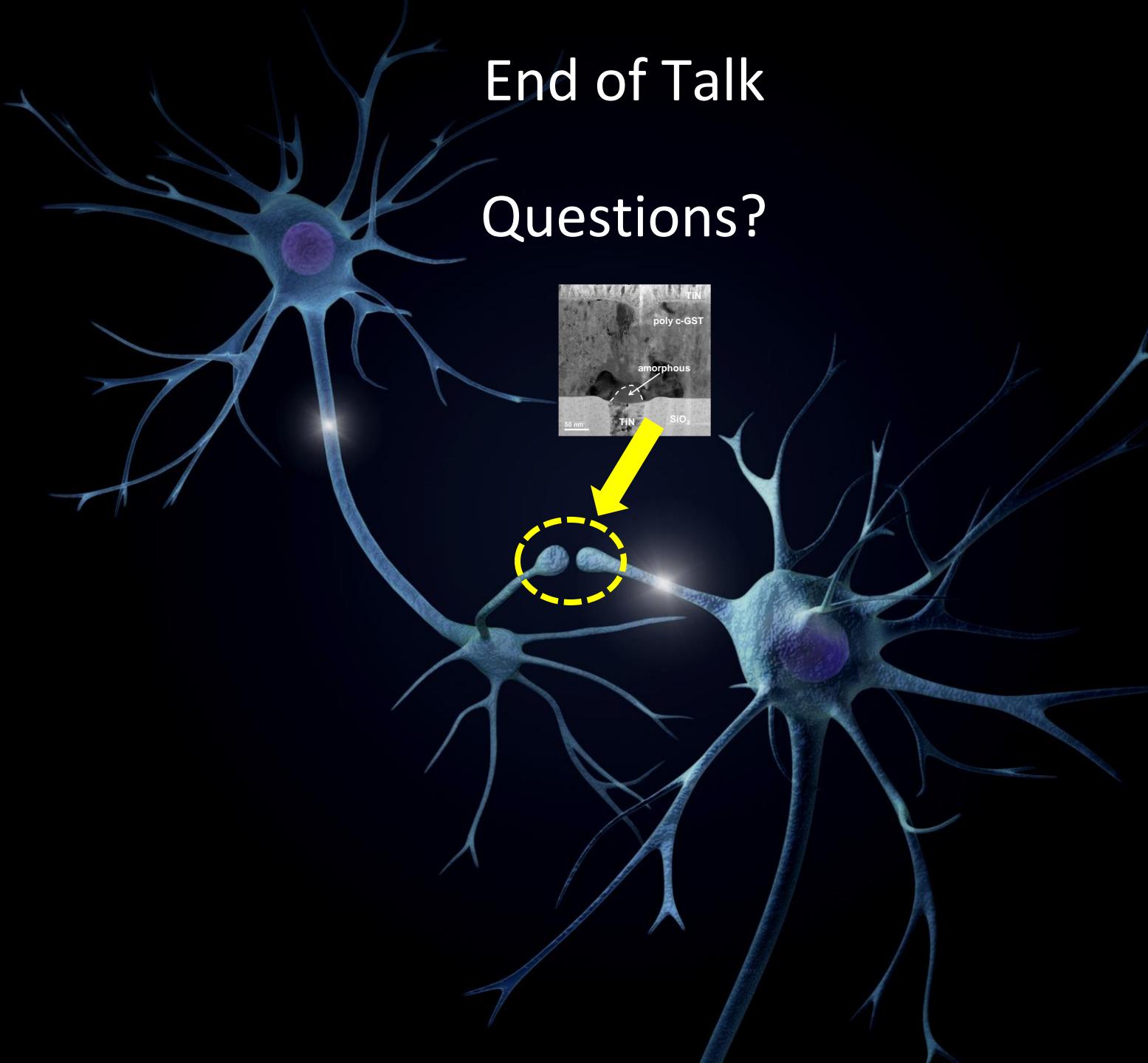
TOSHIBA

 **Lam[®]**
RESEARCH

intel

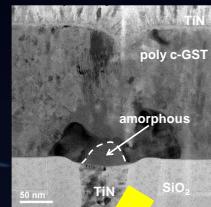
SAMSUNG


tsmc



End of Talk

Questions?



Open Research Questions

1. Functionality → performance/Watt, performance/m² → variability → reliability
2. Scale up (system size), scale down (device size)
3. Role of variability (functionality, performance)
4. Fan-in / fan-out, hierarchical connections, power delivery
5. Low voltage (wire energy ≈ device energy)
6. Stochastic learning behavior → statistical learning rules
7. Meta-plasticity (internal state variables)
8. Timing as an internal variable
9. Learning rules: biological? AI?
10. Algorithm-device co-design
11. Materials/fabrication:
monolithic 3D integration **a must**,
MUST be low temperature

